



## Material Content Data Sheet



<b>Sales Product Name</b>		1EDI20I12AF		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001245998						
<b>Package</b>		PG-DSO-8-51		<b>Weight*</b>		80.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.151	2.68	2.68	26757	26757
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		410	
	non noble metal	iron	7439-89-6	0.660	0.82		8208	
wire	non noble metal	copper	7440-50-8	26.789	33.33	34.20	333283	342004
	noble metal	gold	7440-57-5	0.236	0.29	0.29	2942	2942
	encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1821
plastics		epoxy resin	-	4.733	5.89		58888	
		inorganic material	silicondioxide	60676-86-0	43.919	54.64	60.71	546383
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10125	10125
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1185	1185
glue	plastics	acrylic resin	-	0.175	0.22		2177	
	noble metal	silver	7440-22-4	0.620	0.77	0.99	7718	9895
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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